

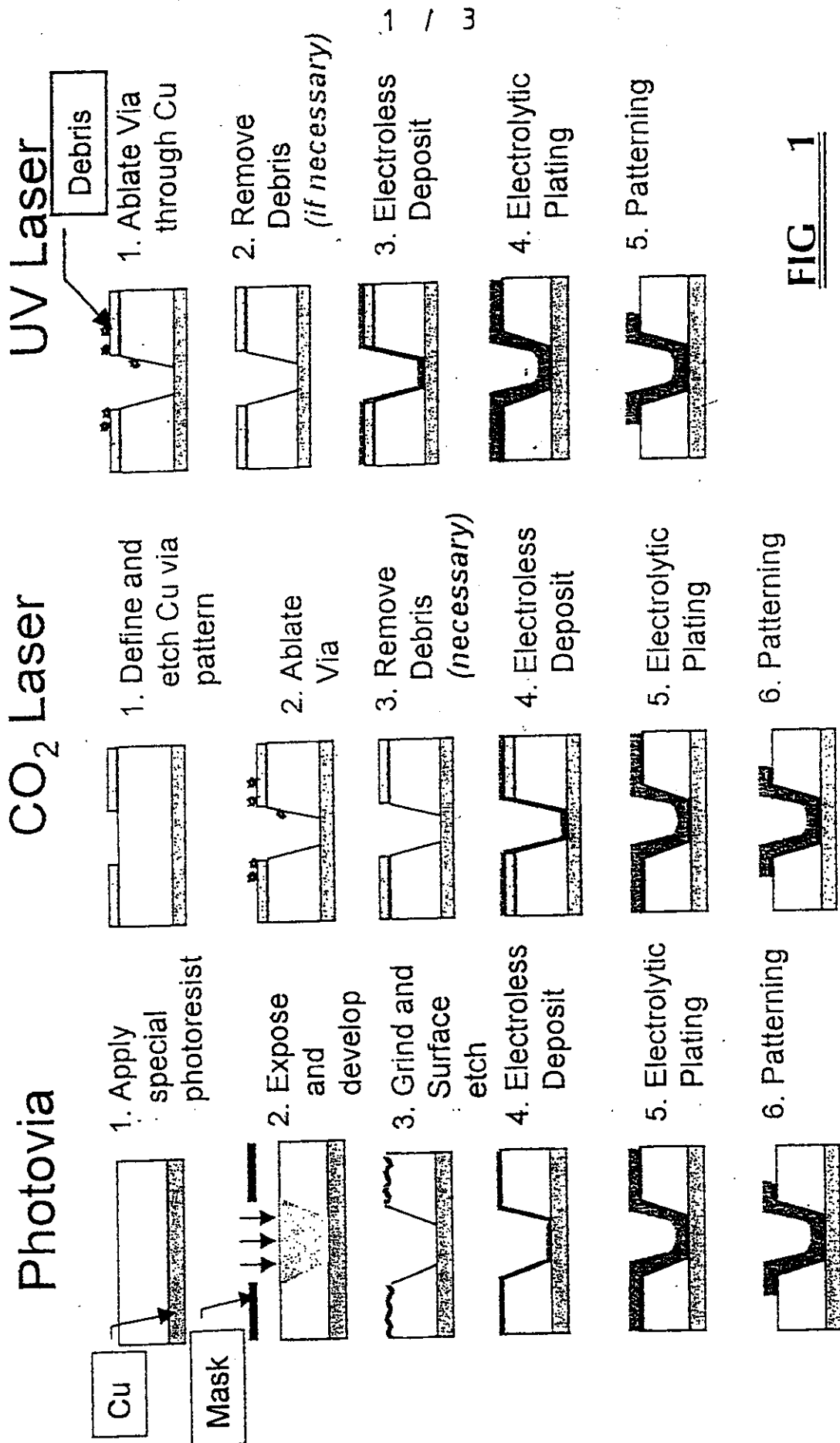


FIG 1

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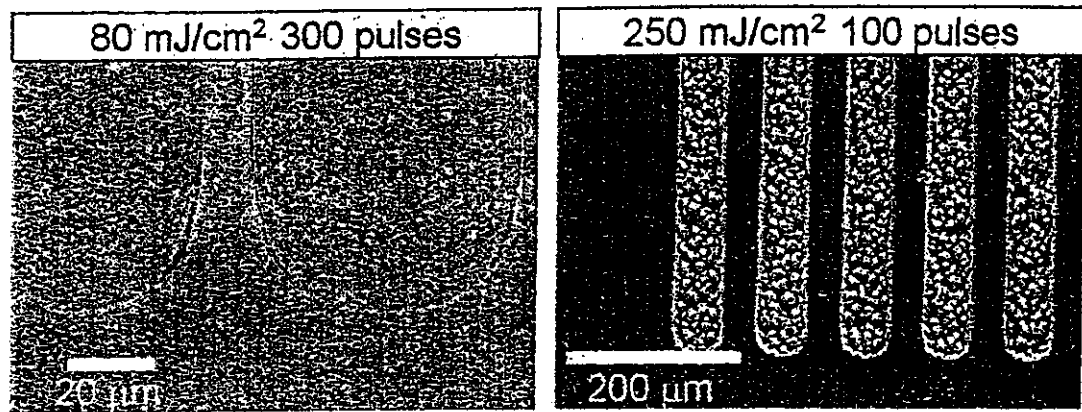
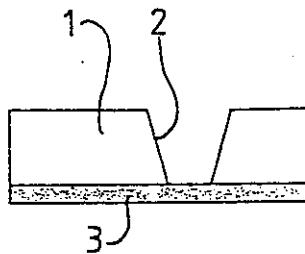
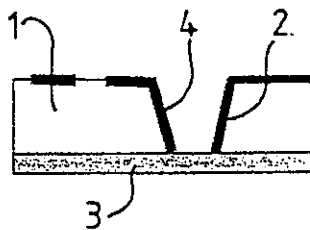


FIG 2



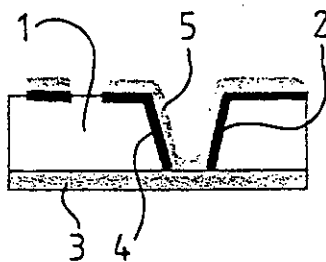
1a. Ablate Via

FIG 3a



1b. Change laser parameters (spot size and fluence) and treat the area for the via pad and circuit

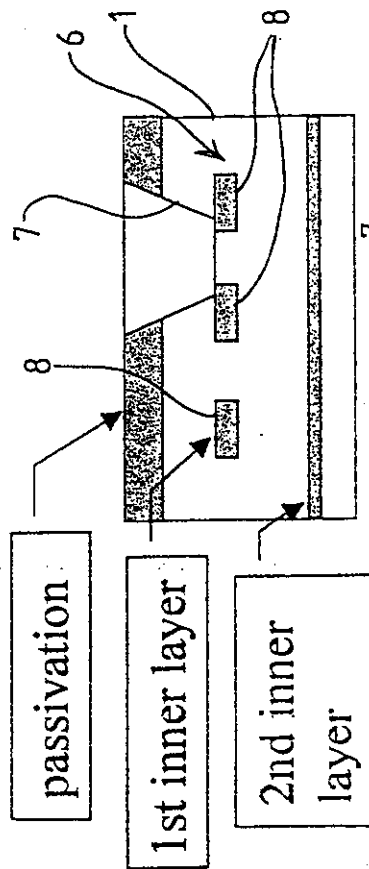
FIG 3b



2. Full electroless build-up for via pad and circuit formation

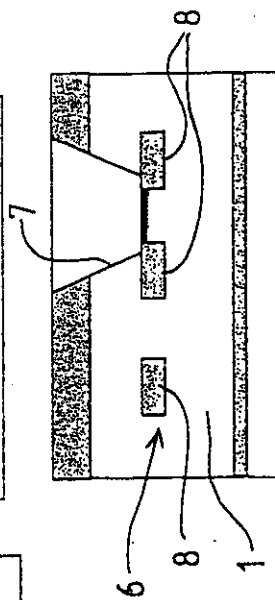
FIG 3c

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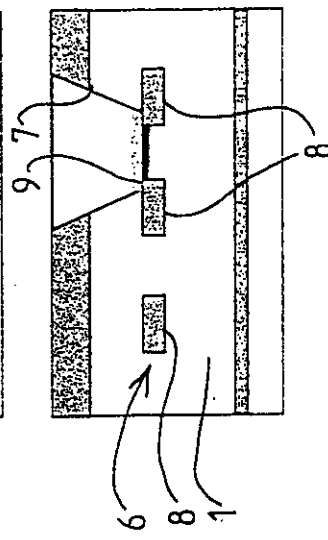
1. Laser drill trench or via

FIG 4a



2. Laser treatment of bottom

FIG 4b



3. Electroless plating for connection

FIG 4c